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Product Change Notification - JAON-17GAPJ777

Date: 15 Jun 2016

Product Category: 16-bit Microcontrollers and Digital Signal Controllers; Analog (Linear & Mixed Signal) AND Interface; Radio Frequency Devices; 8-bit Microcontrollers

Notification subject: CCB 1802 Cancellation Notice: For the qualification of CuPdAu wire, G700LS molding compound and Ag ring plated leadframe in selected products of the 0.25um TSMC wafer technology in 28L SSOP at ANAP.

Notification text: **PCN Status:**
Cancellation notification

Microchip Parts Affected:

This change would have affected selected products of the 0.25um TSMC wafer technology available in 28L SSOP package at ANAP assembly site.

Description of Change:

This qualification was originally presented to qualify palladium coated copper with gold flash (CuPdAu) bond wire, G700LS molding compound and Ag ring plated lead-frame in selected products of the 0.25um TSMC wafer technology available in 28L SSOP package at ANAP assembly site.

Impacts to Data Sheet:

Not Applicable

Reason for Change:

Microchip has decided not to qualify palladium coated copper with gold flash (CuPdAu) bond wire, G700LS molding compound and Ag ring plated lead-frame in selected products of the 0.25um TSMC wafer technology available in 28L SSOP package at ANAP assembly site..

Change Implementation Status:

Not Applicable

Estimated First Ship Date:

Not Applicable

Markings to Distinguish Revised from Unrevised Devices:

Not Applicable

Revision History:

December 03, 2015: Issued initial notification.

June 7, 2016: Issued cancellation notice for the qualification of palladium coated copper with gold flash (CuPdAu) bond wire, G700LS molding compound and Ag ring plated lead-frame in selected products of the 0.25um TSMC wafer technology available in 28L SSOP package at ANAP assembly site.

June 15, 2016: Updated reason for change.

Attachment(s): [PCN_JAON-17GAPJ777_Affected_CPN.pdf](#)
[PCN_JAON-17GAPJ777_Affected_CPN.xls](#)

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Affected Catalog Part Numbers (CPN)

PCN_JAON-17GAPJ777
CATALOG_PART_NBR
DSPIC33FJ06GS102A-E/SS
DSPIC33FJ06GS102A-I/SS
DSPIC33FJ06GS102AT-E/SS
DSPIC33FJ06GS102AT-I/SS
DSPIC33FJ06GS202A-E/SS
DSPIC33FJ06GS202A-I/SS
DSPIC33FJ06GS202AT-E/SS
DSPIC33FJ06GS202AT-I/SS
DSPIC33FJ09GS302-E/SS
DSPIC33FJ09GS302-I/SS
DSPIC33FJ09GS302T-E/SS
DSPIC33FJ09GS302T-I/SS
DSPIC33FJ12GP202-E/SS
DSPIC33FJ12GP202-I/SS
DSPIC33FJ12GP202T-E/SS
DSPIC33FJ12GP202T-I/SS
DSPIC33FJ12MC202-E/SS
DSPIC33FJ12MC202-I/SS
DSPIC33FJ12MC202T-E/SS
DSPIC33FJ12MC202T-I/SS
DSPIC33FJ16GP102-E/SS
DSPIC33FJ16GP102-H/SS
DSPIC33FJ16GP102-I/SS
DSPIC33FJ16GP102T-E/SS
DSPIC33FJ16GP102T-I/SS
DSPIC33FJ16MC102-E/SS
DSPIC33FJ16MC102-H/SS
DSPIC33FJ16MC102-I/SS
DSPIC33FJ16MC102T-E/SS
DSPIC33FJ16MC102T-I/SS
DSPIC33FJ32GP102-E/SS
DSPIC33FJ32GP102-I/SS
DSPIC33FJ32GP102T-E/SS
DSPIC33FJ32GP102T-I/SS
DSPIC33FJ32GP202-E/SS
DSPIC33FJ32GP202-I/SS
DSPIC33FJ32GP202T-E/SS
DSPIC33FJ32GP202T-I/SS
DSPIC33FJ32MC102-E/SS
DSPIC33FJ32MC102-I/SS
DSPIC33FJ32MC102T-E/SS
DSPIC33FJ32MC102T-I/SS
DSPIC33FJ32MC202-E/SS
DSPIC33FJ32MC202-E/SSC25

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Affected Catalog Part Numbers (CPN)

PCN_JAON-17GAPJ777
CATALOG_PART_NBR
DSPIC33FJ32MC202-I/SS
DSPIC33FJ32MC202-I/SSC24
DSPIC33FJ32MC202T-E/SS
DSPIC33FJ32MC202T-I/SS
ENC28J60/SS
ENC28J60-I/SS
ENC28J60T/SS
ENC28J60T-I/SS
MCW1001A-I/SS
MCW1001AT-I/SS
MCWA01-I/SS800
MCWA01T-I/SS800
PIC18F24J10-I/SS
PIC18F24J10T-I/SS
PIC18F24J11-I/SS
PIC18F24J11T-I/SS
PIC18F24J50-I/SS
PIC18F24J50T-I/SS
PIC18F25J10-I/SS
PIC18F25J10T-I/SS
PIC18F25J11-I/SS
PIC18F25J11T-I/SS
PIC18F25J50-I/SS
PIC18F25J50-I/SS022
PIC18F25J50-I/SS024
PIC18F25J50-I/SS027
PIC18F25J50-I/SS028
PIC18F25J50-I/SS029
PIC18F25J50-I/SS030
PIC18F25J50T-I/SS
PIC18F25J50T-I/SSLS
PIC18F26J11-I/SS
PIC18F26J11T-I/SS
PIC18F26J13-I/SS
PIC18F26J13T-I/SS
PIC18F26J50-I/SS
PIC18F26J50-I/SS020
PIC18F26J50T-I/SS
PIC18F26J50T-I/SS020
PIC18F26J50T-I/SS025
PIC18F26J50T-I/SS033
PIC18F26J50T-I/SS034
PIC18F26J53-I/SS
PIC18F26J53T-I/SS

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PCN_JAON-17GAPJ777
CATALOG_PART_NBR
PIC18F27J13-I/SS
PIC18F27J13T-I/SS
PIC18F27J53-I/SS
PIC18F27J53T-I/SS
PIC18LF24J10-I/SS
PIC18LF24J11-I/SS
PIC18LF24J11T-I/SS
PIC18LF24J50-I/SS
PIC18LF24J50T-I/SS
PIC18LF25J10-I/SS
PIC18LF25J10T-I/SS
PIC18LF25J10T-I/SS032
PIC18LF25J10T-I/SS033
PIC18LF25J10T-I/SS035
PIC18LF25J10T-I/SS038
PIC18LF25J10T-I/SS039
PIC18LF25J10T-I/SS040
PIC18LF25J10T-I/SS041
PIC18LF25J10T-I/SSC01
PIC18LF25J11-I/SS
PIC18LF25J11T-I/SS
PIC18LF25J50-I/SS
PIC18LF25J50T-I/SS
PIC18LF26J11-I/SS
PIC18LF26J11T-I/SS
PIC18LF26J13-I/SS
PIC18LF26J13T-I/SS
PIC18LF26J50-I/SS
PIC18LF26J50T-I/SS
PIC18LF26J53-I/SS
PIC18LF26J53T-I/SS
PIC18LF27J13-I/SS
PIC18LF27J13T-I/SS
PIC18LF27J53-I/SS
PIC18LF27J53T-I/SS
PIC24FJ16GA002-E/SS
PIC24FJ16GA002-E/SS020
PIC24FJ16GA002-E/SSC01
PIC24FJ16GA002-I/SS
PIC24FJ16GA002-I/SS020
PIC24FJ16GA002T-E/SS
PIC24FJ16GA002T-E/SS021
PIC24FJ16GA002T-E/SSC02
PIC24FJ16GA002T-I/SS

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Affected Catalog Part Numbers (CPN)

PCN_JAON-17GAPJ777
CATALOG_PART_NBR
PIC24FJ16GA002T-I/SSC03
PIC24FJ16GA002T-I/SSC07
PIC24FJ16GA002T-I/SSC08
PIC24FJ16MC102-E/SS
PIC24FJ16MC102-H/SS
PIC24FJ16MC102-I/SS
PIC24FJ16MC102T-E/SS
PIC24FJ16MC102T-I/SS
PIC24FJ32GA002-E/SS
PIC24FJ32GA002-I/SS
PIC24FJ32GA002-I/SSC07
PIC24FJ32GA002-I/SSC10
PIC24FJ32GA002T-E/SS
PIC24FJ32GA002T-I/SS
PIC24FJ32GA002T-I/SSC10
PIC24FJ32GA102-E/SS
PIC24FJ32GA102-I/SS
PIC24FJ32GA102T-I/SS
PIC24FJ32GB002-I/SS
PIC24FJ32MC102-E/SS
PIC24FJ32MC102-I/SS
PIC24FJ32MC102T-E/SS
PIC24FJ32MC102T-I/SS
PIC24FJ48GA002-E/SS
PIC24FJ48GA002-I/SS
PIC24FJ48GA002-I/SSC04
PIC24FJ48GA002T-I/SS
PIC24FJ64GA002-E/SS
PIC24FJ64GA002-I/SS
PIC24FJ64GA002-I/SSC15
PIC24FJ64GA002T-E/SS
PIC24FJ64GA002T-E/SSC12
PIC24FJ64GA002T-I/SS
PIC24FJ64GA102-I/SS
PIC24FJ64GB002-I/SS
PIC24FJ64GB002T-I/SS
PIC24HJ12GP202-E/SS
PIC24HJ12GP202-I/SS
PIC24HJ12GP202T-E/SS
PIC24HJ12GP202T-I/SS
PIC24HJ32GP202-E/SS
PIC24HJ32GP202-I/SS
PIC24HJ32GP202T-E/SS
PIC24HJ32GP202T-I/SS